PRODUCT/PROCESS CHANGE INFORMATION

SUBJECT	**PRODUCT ALERT / EARLY NOTIFICATION** - DISCONTINUATION OF CURRENT MOLD COMPOUNDS (SAMSUNG SDI) FOR THROUGH HOLE PACKAGES
IMPACTED PRODUCTS	Several products currently in production with Samsung SDI mold compounds, diffused in different Front End technologies and assembled in the following packages: ⬇ TO 220 / DO 220 / I2PAK (except TO220 Clip) ⬇ TO 247/ DO 247 / MAX247 ⬇ ISOTOP ⬇ TO92 ⬇ TO3P-3L ⬇ TO202 ⬇ IPAK Products from Automotive & Discrete Group (ADG) and Analog, MEMS & Sensors Group (AMS) are directly impacted.
MANUFACTURING STEP	Assembly (material: mold compound).
INVOLVED PLANT	ST internal assembly plants as well as subcontractors
CHANGE REASON	Samsung SDI product termination of the following references of molding compound for through hole packages ⬇ SG8200DTA ⬇ SG8200DTB / 1 ⬇ SG-8100G / GS / GSA ⬇ SI-7200DXC ⬇ SG8100GSP ⬇ SI-7200DX2 ⬇ ST-7100HF

CHANGE DESCRIPTION	Replacement of current mold compounds with alternative material. ST is already proceeding with new resins evaluation and qualification, to guarantee adequate products continuity.
TRACEABILITY	By date code and internal traceability to be detailed in PCN to come.
VALIDATION	Validation is based on the different type of packages, required performances and market application requirements. Reference guidelines such as AEC-Q100 (for integrated circuits) and AEC-Q101 (for discrete devices) are taken into account for automotive products. Appropriate technical qualification results and dedicated PCNs will be available and communicated by ST also with the change implementation timeline and samples avaibility.
NOTIFICATION	The change will be notified to customers by PCN sent by product divisions from Q2 2019 depending on the products and packages families.
REPORTS	This is an alert note/early notification, to allow customers to be prepared for managing the change in a short timeframe. Dedicated Product Change Notification (PCN) will follow in forthcoming months, upon products qualification completion.